

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.2	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$		12.7	m Ω
Threshold voltage	$V_{F(TO)}$			1.25	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{Rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$		2.5	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 10 A _{pk} 25 A/ μ s 25 $^{\circ}\text{C}$	200	ns	
Reverse recovery current	I_{rr}		2.75	A	
Reverse recovery charge	Q_{rr}		0.32	μC	
Snap factor	S		0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance junction to case	R_{thJC}	DC operation	1.5	$^{\circ}\text{C/W}$
Maximum thermal resistance junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		40	
Soldering temperature	T_S		260	$^{\circ}\text{C}$
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D ² PAK (SMD-220)	10ETF02S	
			10ETF04S	
			10ETF06S	

Note

- ⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μ m) copper 40 $^{\circ}\text{C/W}$.
For recommended footprint and soldering techniques refer to application note #AN-994.

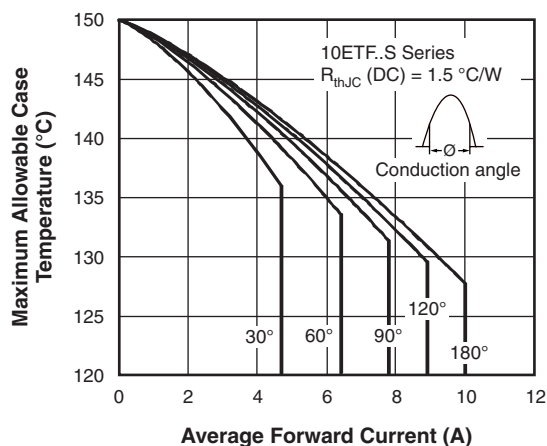


Fig. 1 - Current Rating Characteristics

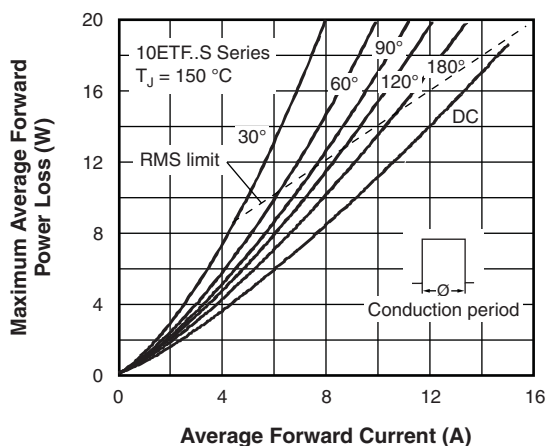


Fig. 4 - Forward Power Loss Characteristics

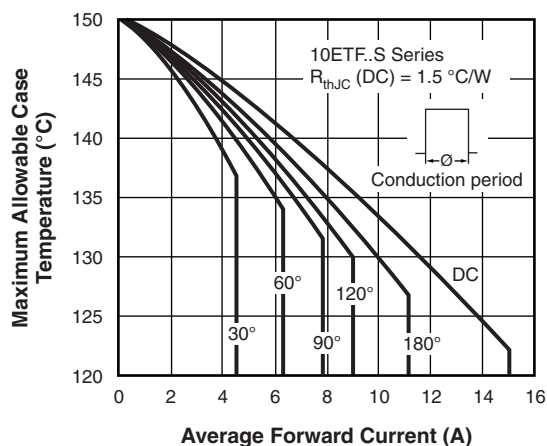


Fig. 2 - Current Rating Characteristics

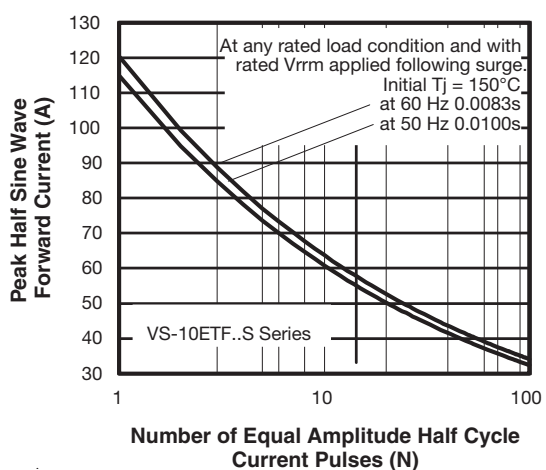


Fig. 5 - Maximum Non-Repetitive Surge Current

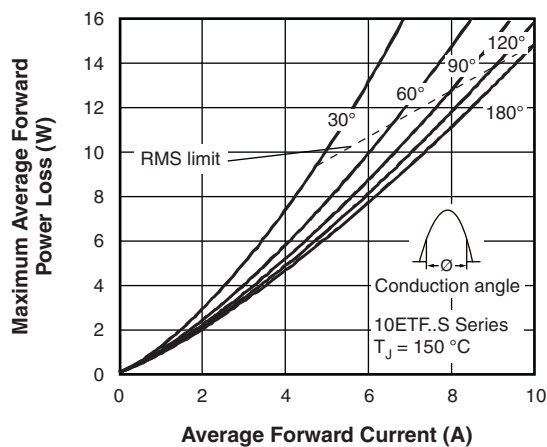


Fig. 3 - Forward Power Loss Characteristics

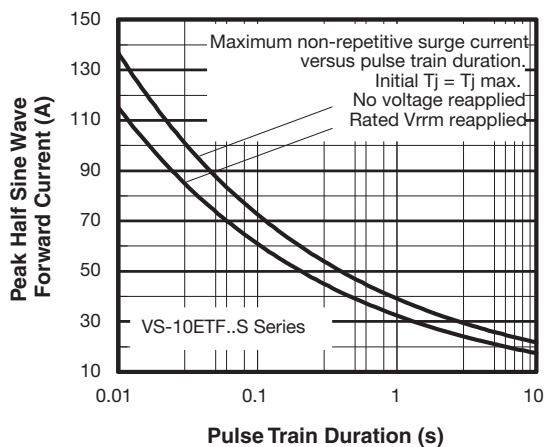


Fig. 6 - Maximum Non-Repetitive Surge Current

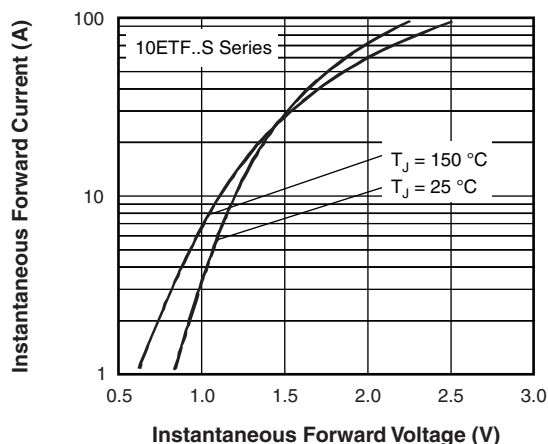


Fig. 7 - Forward Voltage Drop Characteristics

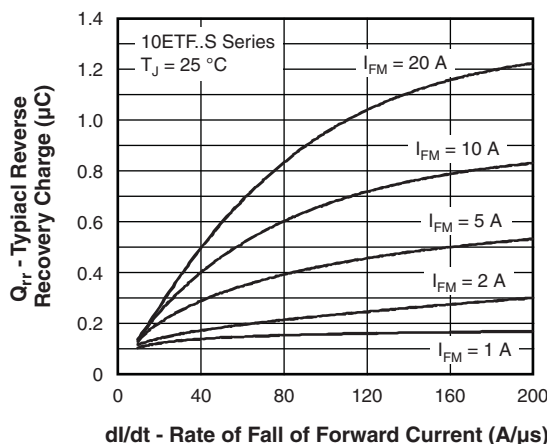


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

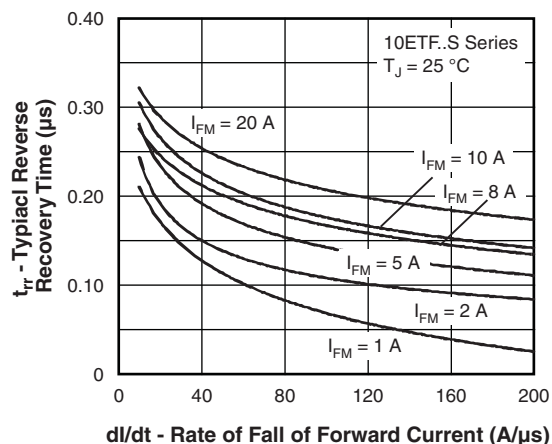


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

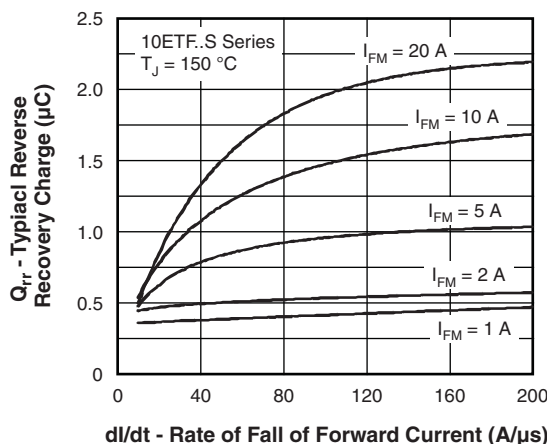


Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

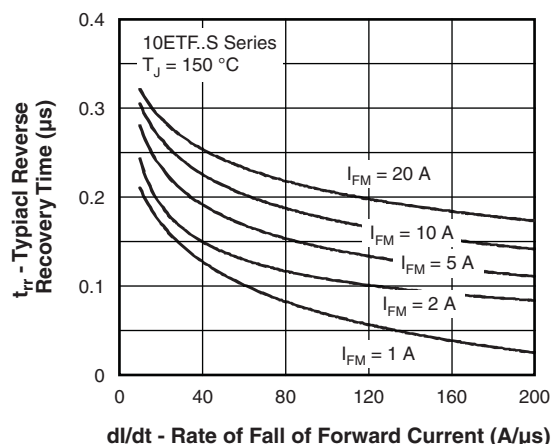


Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

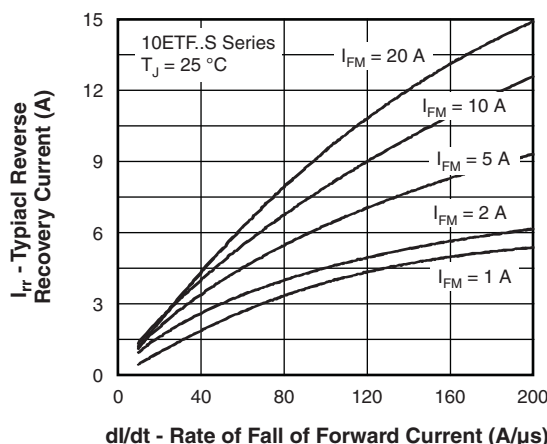
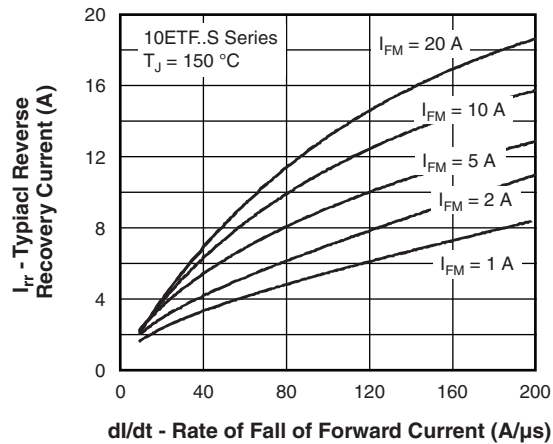
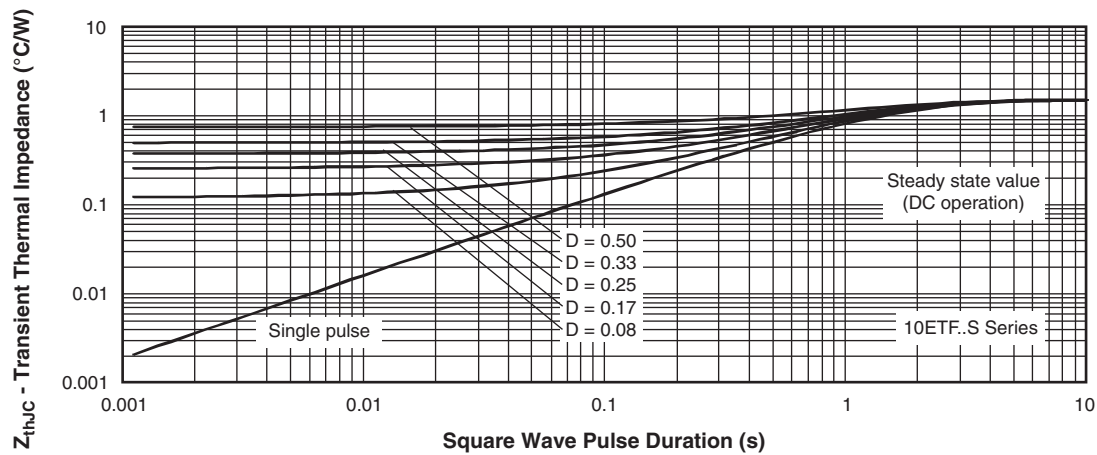


Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 14 - Thermal Impedance Z_{thJC} Characteristics



ORDERING INFORMATION TABLE

Device code	VS-	10	E	T	F	06	S	TRL	PbF
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Package:
T = D²PAK (TO-220AC)
- 5** - Type of silicon:
F = fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM}
- 7** - S = surface mountable
- 8** -
 - None = tube
 - TRR = tape and reel (right oriented)
 - TRL = tape and reel (left oriented)
- 9** - PbF = lead (Pb)-free

02 = 200 V
04 = 400 V
06 = 600 V

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETF02SPbF	50	1000	Antistatic plastic tubes
VS-10ETF02STRRPbF	800	800	13" diameter reel
VS-10ETF02STRLPbF	800	800	13" diameter reel
VS-10ETF04SPbF	50	1000	Antistatic plastic tubes
VS-10ETF04STRRPbF	800	800	13" diameter reel
VS-10ETF04STRLPbF	800	800	13" diameter reel
VS-10ETF06SPbF	50	1000	Antistatic plastic tubes
VS-10ETF06STRRPbF	800	800	13" diameter reel
VS-10ETF06STRLPbF	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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